A B S T R A C T

First (30) and second (40) frame bodies are used to fabricate a semiconductor device. The first frame body (30) includes a die pad (33). The second frame body (40) includes a plurality of leads (42). The die pad is depressed by a predetermined amount (h) which is equal or greater than the thickness of a semiconductor chip (50) to be mounted on the die pad. The two frame bodies are welded, and wire bonding and cutting of the leads are performed.

Refer to Figures 7A to 7J

This Sheet Has Been Replaced

